

**In the Claims**

Cancel claims ~~13~~, ~~21~~ and ~~28~~.

The claims have been amended as follows:

1 1. (Currently Amended) A method to enhance integrated circuit device heat  
2 dissipation comprising the steps of:  
3 providing an integrated circuit device having a surface;  
4 providing a flexible corrugated tape strip of a thermal conductive material having a flat  
5 flexible tape strip of a thermal conductive material bonded to ~~one~~ each side  
6 thereto forming a ~~single~~ double-faced flexible corrugated tape strip article; and  
7 adhering the double-faced flexible corrugated tape strip article to the surface of the  
8 integrated circuit device.

1 2. (Canceled)

1 3. (Currently Amended) The method of claim 1 wherein ~~the~~ both tape strips is are  
2 metal and ~~is~~ copper or aluminum.

1 4. (Previously Amended) The method of claim 3 wherein the thickness of the tape  
2 strip used to make the corrugated tape strip and the flat flexible tape strip are both about  
3 0.5 mil to 10 mil.

1 5. (Withdrawn)

1 6. (Original) The method of claim 4 wherein the corrugations in the strip are in the  
2 shape of a repeating series of convex and concave portions comprising sidewall portions,  
3 top portions and bottom portions.

1 7.-10. (Withdrawn)

1 11. (Canceled)

1 12. (Previously Amended) The method of claim 1 wherein the flat flexible tape strip  
2 article has an adhesive thereon on the side to be adhered to the integrated circuit device.

1 13. (Canceled)

1 14.-15. (Withdrawn)

1 16. (Currently Amended) A method to enhance integrated circuit device heat  
2 dissipation comprising the steps of:

3 providing an integrated circuit device having a surface;

4 providing a tape strip of flexible flat thermal conductive material;

5 forming corrugations in the tape strip of the flexible thermal conductive material;

6 bonding a thermal conductive material flat tape strip to ~~one~~each side of the flexible  
7 corrugated tape strip forming a ~~single~~double-faced flexible corrugated tape strip  
8 article; and  
9 adhering the ~~single~~double-faced flexible corrugated tape strip article to the surface of  
10 the integrated circuit device.

1 17.-18. (Withdrawn)

1 19. (Canceled)

20. (Currently Amended) The method of claim 16 wherein an adhesive is applied to  
2 the side of the ~~single~~double-faced corrugated tape strip article to be adhered to the  
3 integrated circuit device.

1 21. (Canceled)

1 22.-23. (Withdrawn)

24. (Currently Amended) An article of manufacture for dissipating heat for integrated  
2 circuit devices comprising a corrugated flexible tape strip of thermal conductive material  
3 having a flat flexible tape strip of a thermal conductive material bonded to one ~~side~~each  
4 thereto forming a ~~single~~double-faced flexible corrugated tape strip article.

1 25.-26. (Canceled)

1 27. (Previously Amended) The article of claim 24 wherein the flat tape strip of thermal  
2 conductive material has an adhesive on the side to be adhered to an integrated circuit  
3 device.

 1 28. (Canceled)

1 29.-34. (Canceled)

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